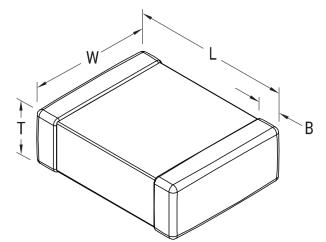


CKC18C622KCGAC7210

KC-LINK Comm COG, Ceramic, 6200 pF, 10%, 500 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1812



Click here for the 3D model.

Dimensions			
Chip Size	1812		
L	4.5mm +/-0.3mm		
W	3.2mm +/-0.3mm		
Т	1.4mm +/-0.15mm		
В	0.6mm +/-0.35mm		

Pa	Packaging Specifications	
F	Packaging	T&R, 330mm, Plastic Tape
F	Packaging Quantity	4000

General Information				
Series	KC-LINK Comm COG			
Style	SMD Chip			
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I			
Features	Ultra-Stable, Low Loss, Class I			
RoHS	Yes			
Termination	Tin			
Marking	No			
AEC-Q200	No			
Component Weight	67 mg			
Shelf Life	78 Weeks			
MSL	1			

Specifications				
Capacitance	6200 pF			
Measurement Condition	1 kHz 1.0Vrms			
Capacitance Tolerance	10%			
Voltage DC	500 VDC			
Dielectric Withstanding Voltage	750 VDC			
Temperature Range	-55/+150°C			
Temperature Coefficient	COG			
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms			
Dissipation Factor	0.1% 1 kHz 1.0Vrms			
Aging Rate	0% Loss/Decade Hour			
Insulation Resistance	100 GOhms			

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.